



#7 C.L. 4/23/02 PATENT

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December 31, 2001

Date

Rena Iov

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Setho Sing Fee, Lim Thiam Chye and Eric Tan Swee Seng
Application No. : 09/944,246 Confirmation No.: 1798
Filed : August 30, 2001
For : PACKAGED MICROELECTRONIC DEVICES AND METHODS
OF FORMING SAME

Art Unit : 2811
Docket No. : 108298630US
Date : December 31, 2001

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Commissioner for Patents
Washington, DC 20231

TRANSMITTAL OF FORMAL DRAWINGS

Sir:

Enclosed please find nine sheets of formal drawings (Figures 1A-11) for the above-identified application.

Respectfully submitted,
Perkins Coie LLP

Edward S. Hotchkiss

Edward S. Hotchkiss
Registration No. 33,904

ESH:ri

Enclosures:

9 Sheets of Drawings (Figs. 1A-11)

PERKINS COIE LLP
P.O. Box 1247
Seattle, Washington 98111-1247
(206) 583-8888
FAX: (206) 583-8500